

NPN SILICON PLANAR MEDIUM POWER TRANSISTORS IN SOT89

Features

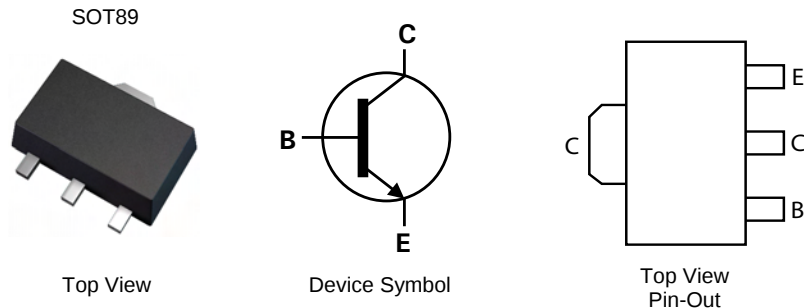
- $I_C = 1A$ Continuous Collector Current
- Low Saturation Voltage $V_{CE(sat)} < 500mV$ @ 0.5A
- Gain Groups 10 and 16
- Epitaxial Planar Die Construction
- Complementary PNP types: BCX51, 52, and 53
- **Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP capable (Note 4)**

Mechanical Data

- Case: SOT89
- Case Material: Molded Plastic, "Green" Molding Compound
- UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Leads, Solderable per MIL-STD-202 Method 208 
- Weight: 0.072 grams (Approximate)

Applications

- Medium Power Switching or Amplification Applications
- AF driver and output stages

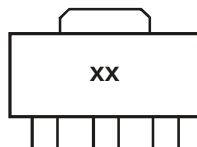


Ordering Information (Notes 4 & 5)

Product	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
BCX54TA	AEC-Q101	BA	7	12	1,000
BCX5410TA	AEC-Q101	BC	7	12	1,000
BCX5416TA	AEC-Q101	BD	7	12	1,000
BCX5416-13R	AEC-Q101	BD	13	12	4,000
BCX55TA	AEC-Q101	BE	7	12	1,000
BCX5510TA	AEC-Q101	BG	7	12	1,000
BCX5516TA	AEC-Q101	BM	7	12	1,000
BCX56TA	AEC-Q101	BH	7	12	1,000
BCX5610TA	AEC-Q101	BK	7	12	1,000
BCX5616TA	AEC-Q101	BL	7	12	1,000
BCX5616QTA	Automotive	BL	7	12	1,000
BCX5616TC	AEC-Q101	BL	13	12	4,000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See <http://www.diodes.com> for more information about Diodes Incorporated's definitions of Halogen and Antimony free, "Green" and Lead-Free.
 3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified.
 5. For packaging details, go to our website at <http://www.diodes.com>

Marking Information



xx = Product Type Marking Code, as follows:

BCX54 = BA	BCX55 = BE	BCX56 = BH
BCX5410 = BC	BCX5510 = BG	BCX5610 = BK
BCX5416 = BD	BCX5516 = BM	BCX5616 = BL

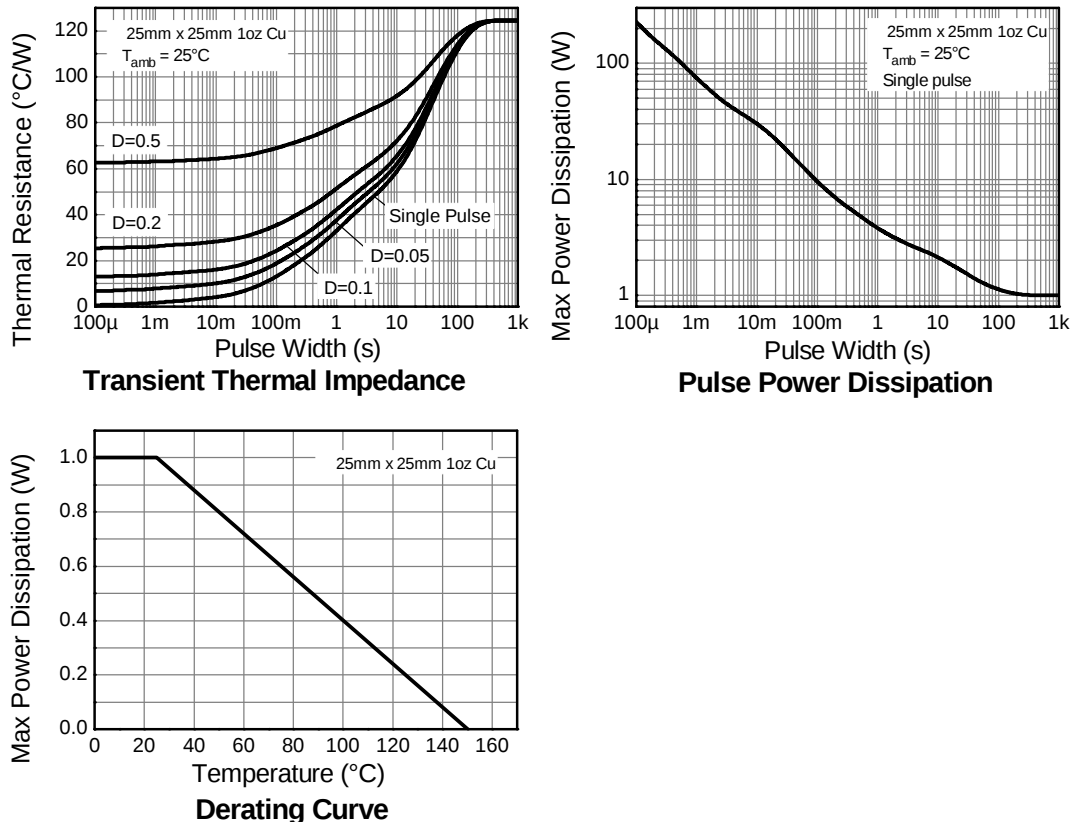
Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	BCX54	BCX55	BCX56	Unit
Collector-Base Voltage	V _{CBO}	45	60	100	V
Collector-Emitter Voltage	V _{CEO}	45	60	80	V
Emitter-Base Voltage	V _{EBO}	6			V
Continuous Collector Current	I _C	1			A
Peak Pulse Collector Current	I _{CM}	1.5			
Continuous Base Current	I _B	100			mA
Peak Pulse Base Current	I _{BM}	200			

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P_D	1	W
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\theta JA}$	124	$^\circ\text{C/W}$
Thermal Resistance, Junction to Leads (Note 7)	$R_{\theta JL}$	10.0	$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +150	$^\circ\text{C}$

Notes: 6. For a device surface mounted on 25mm X 25mm FR4 PCB with high coverage of single sided 1 oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
 7. Thermal resistance from junction to solder-point (on the exposed collector pad).

Thermal Characteristics


Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic		Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BCX54	BV_{CBO}	45	—	—	V	$I_C = 100\mu\text{A}$
	BCX55		60				
	BCX56		100				
Collector-Emitter Breakdown Voltage (Note 8)	BCX54	BV_{CEO}	45	—	—	V	$I_C = 10\text{mA}$
	BCX55		60				
	BCX56		80				
Emitter-Base Breakdown Voltage		BV_{EBO}	6	—	—	V	$I_E = 100\mu\text{A}$
Collector Cut-off Current		I_{CBO}	-	—	0.1 20	μA	$V_{CB} = 30\text{V}$ $V_{CB} = 30\text{V}, T_A = +150^\circ\text{C}$
Emitter Cut-off Current		I_{EBO}	-	—	20	nA	$V_{EB} = 5\text{V}$
Static Forward Current Transfer Ratio (Note 6)	All versions	h_{FE}	25	—	-	—	$I_C = 5\text{mA}, V_{CE} = 2\text{V}$
			40	—	250		$I_C = 150\text{mA}, V_{CE} = 2\text{V}$
	10 gain grp		25	—	-		$I_C = 500\text{mA}, V_{CE} = 2\text{V}$
	16 gain grp		63	—	160		$I_C = 150\text{mA}, V_{CE} = 2\text{V}$
Collector-Emitter Saturation Voltage (Note 8)		$V_{CE(sat)}$	—	—	0.5	V	$I_C = 500\text{mA}, I_B = 50\text{mA}$
Base-Emitter Turn-On Voltage (Note 8)		$V_{BE(on)}$	—	—	1.0	V	$I_C = 500\text{mA}, V_{CE} = 2\text{V}$
Transition Frequency		f_T	150	—	-	MHz	$I_C = 50\text{mA}, V_{CE} = 10\text{V}$ $f = 100\text{MHz}$
Output Capacitance		C_{obo}	—	—	25	pF	$V_{CB} = 10\text{V}, f = 1\text{MHz}$

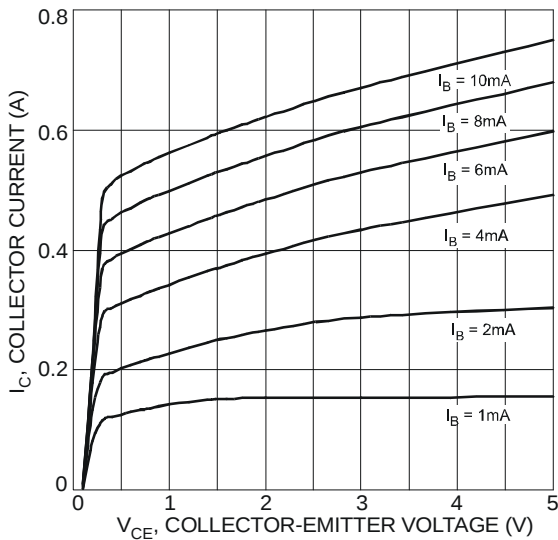
 Notes: 8. Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$. Duty cycle $\leq 2\%$.


Fig. 1 Typical Collector Current vs. Collector-Emitter Voltage

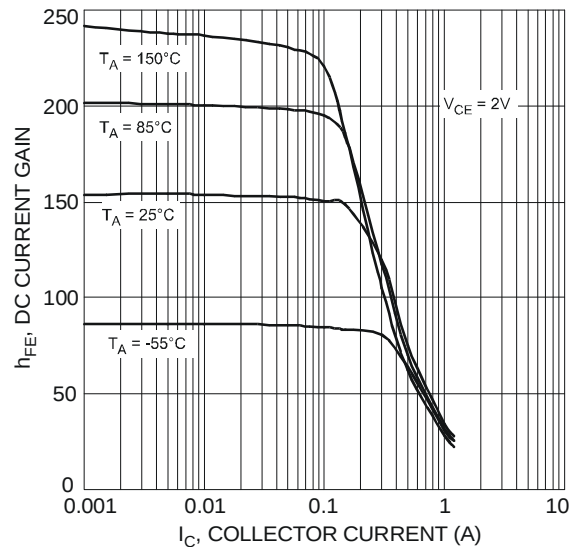


Fig. 2 Typical DC Current Gain vs. Collector Current

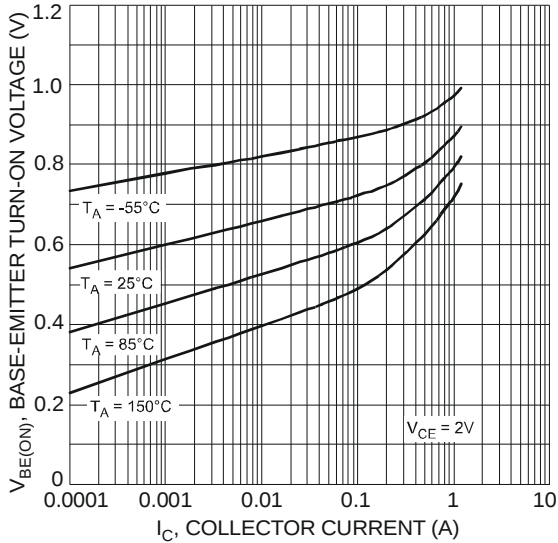


Fig. 3 Typical Base-Emitter Turn-On Voltage vs. Collector Current

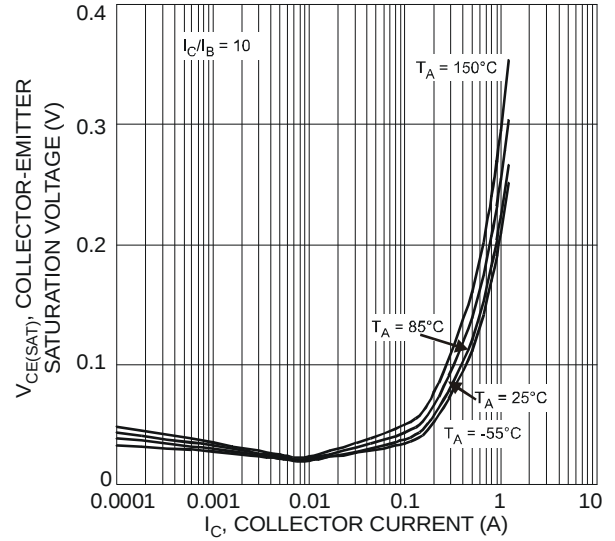


Fig. 4 Typical Collector-Emitter Saturation Voltage vs. Collector Current

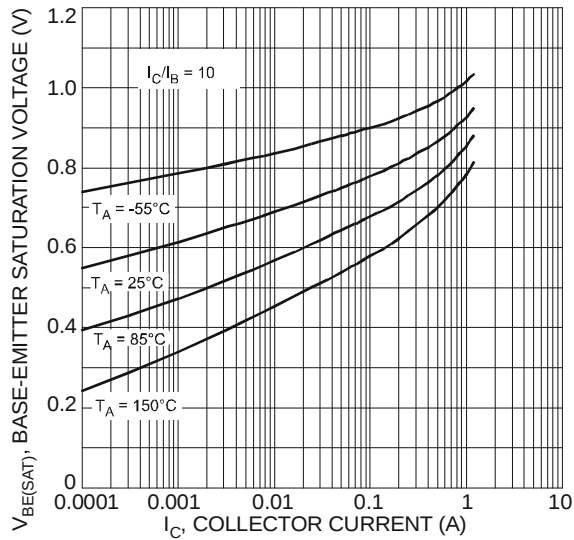


Fig. 5 Typical Base-Emitter Saturation Voltage vs. Collector Current

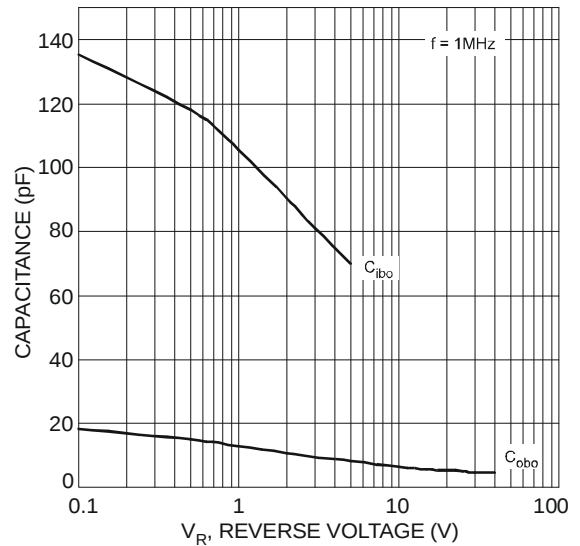


Fig. 6 Typical Capacitance Characteristics

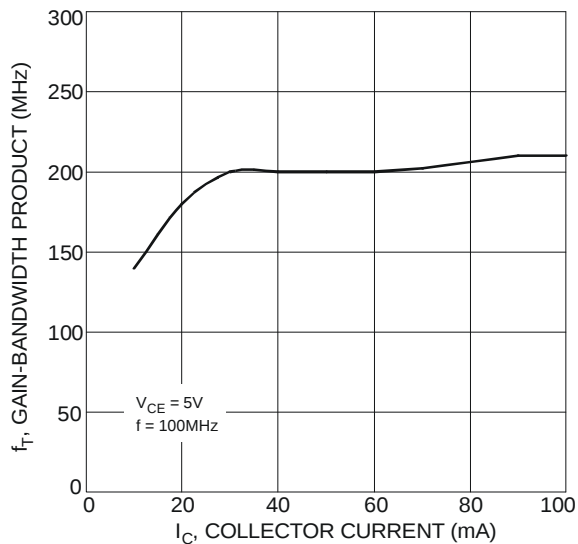
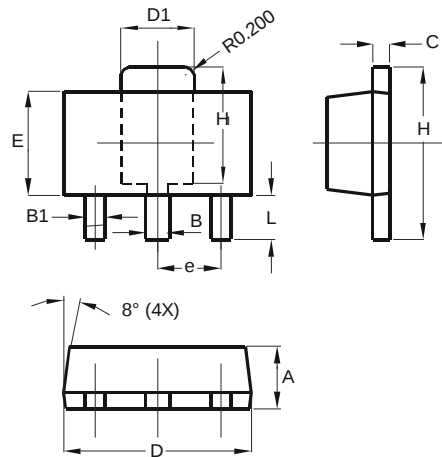


Fig. 7 Typical Gain-Bandwidth Product vs. Collector Current

Package Outline Dimensions

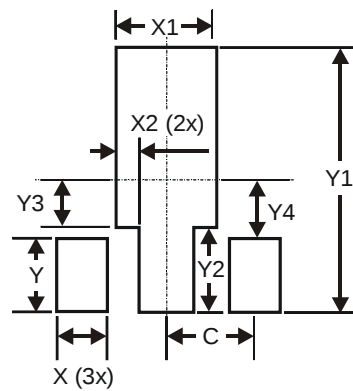
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SOT89		
Dim	Min	Max
A	1.40	1.60
B	0.44	0.62
B1	0.35	0.54
C	0.35	0.44
D	4.40	4.60
D1	1.62	1.83
E	2.29	2.60
e	1.50 Typ	
H	3.94	4.25
H1	2.63	2.93
L	0.89	1.20
All Dimensions in mm		

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
X	0.900
X1	1.733
X2	0.416
Y	1.300
Y1	4.600
Y2	1.475
Y3	0.950
Y4	1.125
C	1.500

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Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9